

SOT1354-1

plastic, extremely thin fine-pitch ball grid array package; 16 balls

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|---|
| Terminal position code | B (bottom) |
| Package type descriptive code | XFBGA16 |
| Package type industry code | XFBGA16 |
| Package style descriptive code | XFBGA (extremely thin fine-pitch ball grid array) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| Mounting method type | S (surface mount) |
| Issue date | 27-8-2013 |

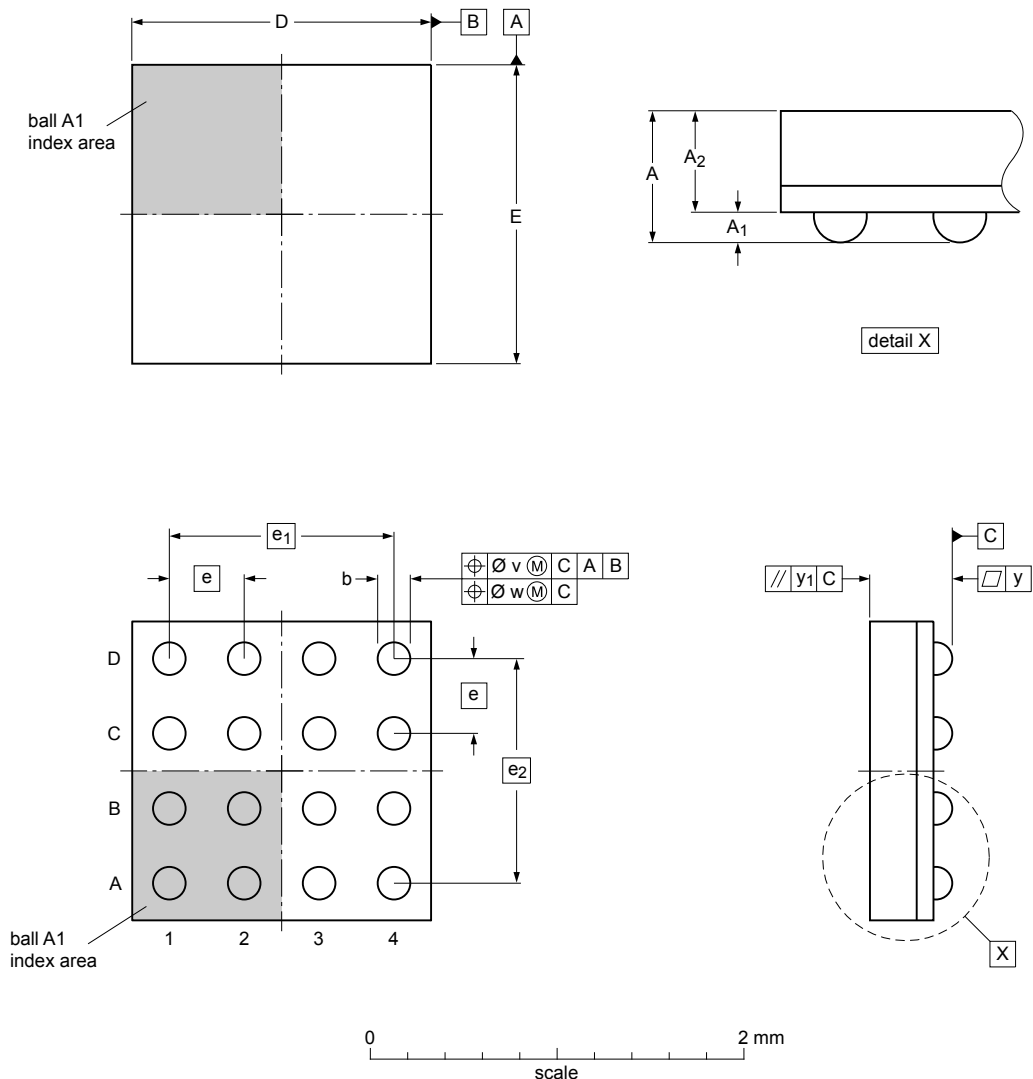
Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-------|-----|-------|------|------|
| D | package length | 1.5 | - | 1.6 | 1.7 | mm |
| E | package width | 1.5 | - | 1.6 | 1.7 | mm |
| A | seated height | [tbd] | - | [tbd] | 0.5 | mm |
| A ₂ | package height | 0.33 | - | 0.34 | 0.35 | mm |
| e | nominal pitch | - | - | 0.4 | - | mm |
| n ₂ | actual quantity of termination | - | - | 16 | - | |



2. Package outline

XFBGA16: plastic, extremely thin fine-pitch ball grid array package; 16 balls SOT1354-1



Dimensions (mm are the original dimensions)

| Unit | A | A ₁ | A ₂ | b | D | E | e | e ₁ | e ₂ | v | w | y | y ₁ |
|------|-----|----------------|----------------|-------|-----|-----|-----|----------------|----------------|------|------|------|----------------|
| max | 0.5 | 0.15 | 0.35 | 0.205 | 1.7 | 1.7 | | | | | | | |
| nom | | 0.10 | 0.34 | 0.175 | 1.6 | 1.6 | 0.4 | 1.2 | 1.2 | 0.15 | 0.05 | 0.08 | 0.1 |
| min | | 0.05 | 0.33 | 0.145 | 1.5 | 1.5 | | | | | | | |

sot1354-1_po

| Outline version | References | | | European projection | Issue date |
|-----------------|------------|-------|-------|---------------------|----------------------|
| | IEC | JEDEC | JEITA | | |
| SOT1354-1 | --- | --- | --- | | 13-03-26 13-08-27 |

Fig. 1. Package outline XFBGA16 (SOT1354-1)

3. Legal information

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